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# (12) United States Patent

Hirano et al.

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(54) ACTINIC RAY-SENSITIVE OR
RADIATION-SENSITIVE RESIN
COMPOSITION, RESIST FILM USING THE
SAME, PATTERN FORMING METHOD,
MANUFACTURING METHOD OF
ELECTRONIC DEVICE, AND ELECTRONIC
DEVICE

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(58) Field of Classification Search

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# (57) ABSTRACT

There is provided an actinic ray-sensitive or radiation-sensitive resin composition comprising (P) a resin containing a repeating unit represented by the specific formula (1) and a repeating unit represented by the specific formula (A); a resist film formed using the actinic ray-sensitive or radiation-sensitive resin composition; a pattern forming method comprising (i) a step of forming a film from the actinic ray-sensitive or radiation-sensitive resin composition, (ii) a step of exposing the film, and (iii) a step of developing the exposed film by using a developer to form a pattern; a method for manufacturing an electronic device, comprising the pattern forming method, and an electronic device manufactured by the manufacturing method of an electronic device.

### 20 Claims, No Drawings